shortcourse

TMS2012
141st Annual Meeting & Exhibition

March 11 – 15, 2012 • Walt Disney World Swan & Dolphin Resort • Orlando, Florida

8th Annual TMS Lead Free Solder and Interconnect Technology Workshop

Sunday, March 11, 2012 • 9:00 a.m. – 4:30 p.m.

Member fee: **$15**
Late Member fee: **$25**

Nonmember fee: **$125**
Late Nonmember fee: **$175**

Course Description and Objectives:
Through presentations and extensive discussion regarding key topics, this workshop will provide a bridge between companies, academic research groups, national laboratories, and consortia and will lead to the materials science fundamentals necessary for further understanding and future industry applications. The workshop will be focused on 3D packaging technology and other important issues. Especially in this year, the applications of Pb-free solder in green technology will be addressed.

Workshop Topics
- 3D packaging technology and TSV from an industry and academic point of view
- Pb-free applications in green technology
- Reliability in consumer electronics
- Solder and interconnects in extreme environment
- Future directions in new solder alloy compositions
- Mechanics of deformation in Pb-free solder joints
- Pb-free board assembly related issues and solutions

Who should attend:
The workshop will be of interest to the people who want to know the hot topics in the electronic packaging society. Researchers, professors and students from the academic institutes should attend to learn the advanced knowledge in this field.

Instructors:
Dr. Ho-Ming Tong - ASE Global

Dr. Taekyu Lee - Cisco

Prof. Suganuma - Osaka University

Prof. Dasgupta - University of Maryland

Additional speakers from the industry and the research institute in the field of 3D-IC will be invited to present their works or share their viewpoints